ICEP2011 Advanced Program (13, April)

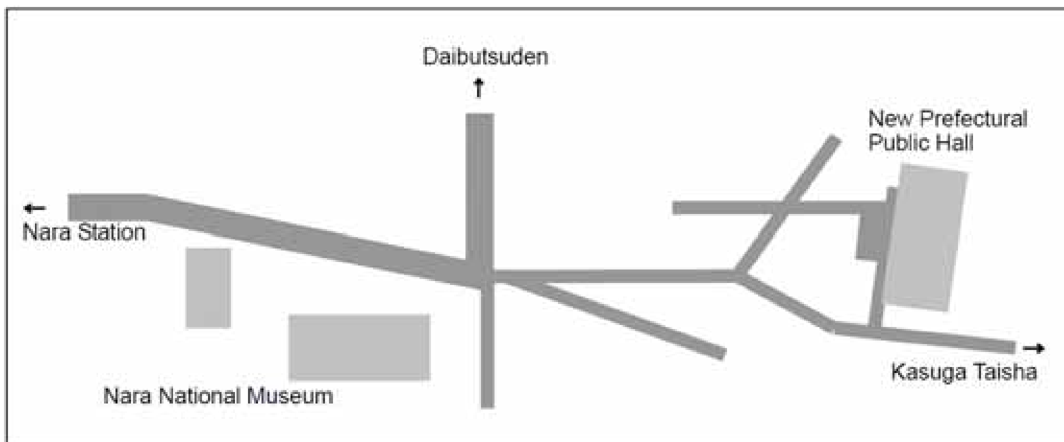
13, April	Room A	Room B	Room C	Room D
	WA1:MFG-1	WB1	WC1:Thermal Management-1	WD1:DMR-R-1
10:00	WA1-1 Analysis on wirebond mechanical integrity of ultra fine pitch wirebond on ultra low-k(ULK) device T.Hisada, T.Aoki, S.Harada, J.C.Malinowski, IBM Japan / Japan	WB1-1 Room Temperature Bonding of Germanium with Gallium Arsenide M.Howlader[1], F.Zhang[1], J.Jeon[2], M.J.Kim[2], [1]McMaster University, [2]University of Texas at Dallas / Canada, U.S.A.	WC1-1 Electro-Thermal Analysis and Monte Carlo Simulation for Thermal Design of Si Devices T.Hatakeyama[1], M.Ishizuka[1], S.Nakagawa[1], K.Fushinobu[2], [1]Toyama Prefectural University, [2]Tokyo University of Technology / Japan	WD1-1 Mechanical and electrical reliability of electroplated copper thin film interconnections N.Murata, N.Saito, F.Endo, K.Tamakawa, K.Suzuki, H.Miura, Tohoku University / Japan
10:25	WA1-2 Maximize Memory Capacity Package with Highest Quality and Lowest Cost D.Fann, PowerTech / Taiwan, R.O.C.	WB1-2 Surface activated bonding of Si/SiC for high power electronic devices F.Zhang[1], M.R.Howlader[1], A. Yamauchi[2], [1]McMaster University, [2]Bondtech / Canada, Japan	WC1-2 Electro-thermal scaling analysis of Si MOSFETs with device length typically larger than 100 nm K.Fushinobu[1], T.Hatakeyama[2], [1]Tokyo Institute of Technology, [2]Toyama Prefectural University / Japan	WD1-2 Fracture Strength Characterization of Silicon Die for the Thin Electronic Modules N.Ota, Dai Nippon Printing / Japan
10:50	WA1-3 Stress Simulation of Underfill Materials in Flip Chip Package T.Sato, Namics / Japan	(11:00) WB2:RF WB2-1 The Correlation between Imbalance Component and EM Radiation from a Differential-Paired Line with Different Length Y.Kayano, K.Mimura, H.Inoue, Akita University / Japan	WC1-3 Numerical Study of the Thermal Transfer between Adhesive and CNTs Y.Zhang[1], S.Wang[1], Z.Hu[1], J.Liu[1,2], [1]Shanghai University, [2]Chalmers University of Technology / China, Sweden	WD1-3 Parametric Study on the BGA Packaging Optimization Y.K.Kim, J.C.Kim, J.Choi, Korea Aerospace University / Korea
11:15	WA2:MFG-2		WC2:Thermal Management-2	WD1:DMR-R-2
11:25	WA2-1 Development of wafer-level underfill bonding process for 3D chip stacking T.F.Yang, K.S.Kao, J.Y.Chang, C.J.Zhan, Industrial Technology Research Institute / Taiwan, R.O.C.	WB2-2 Design and Test of RF Front End for UHF RFID Tag C.C.Huang, K.W.Ku, W.D.Tu, Yuan Ze University / Taiwan	WC2-1 Introduction to Application of Boiling Heat Transfer to High Heat Flux Cooling Technology in Power Electronics K.Suzuki[1], K.Yuki[1], M.Mochizuki[2], [1]Tokyo University of Science, Yamaguchi, [2]Fujikura / Japan	WD2-1 Reliability Desigs for 40 nm ELK Flip-chip Packages with Copper Pillar Bumps Y.S.Lai, M.K.Shih, C.C.Lee, B.K.Appelt, C.Cheung, Advanced Semiconductor Engineering / Taiwan
11:50	WA2-2 Process Optimization for Molded Underfill to Reduce Air-trap in a System-in-Package Y.H.Yeh, Y.Amanoand, S.C.Hsu, H.H.Hsu, PowerTech / Taiwan R.O.C.	WB2-3 Structural Design of Transmitter and Receiver Electrodes for Improvement of Transmission Characteristics in Human -Body Communication D.Muramatsu, Tokyo University of Science / Japan	WC2-2 Cooling performance of a two phase (vapor-liquid) flow cooling system M.Chiba, NEC / Japan	WD2-2 Investigation of PWB Resin Laminate and Its Relation with the Pad Cratering Resistance S.W.R.Lee, C.Yang, F.Song, Hong Kong University of Science & Technology / China
12:15	WA2-3 Effects of Edge and Corner Bond Underfills on Board Level Shear Strength of Lead-free Package-on-Package H.B.Shi, T.Ueda, Waseda University / Japan	WB2-4 An Antenna Apertured with a Half-Semicircle and -Trapezoid in Metal Housing Wall of Electronic Equipments F.Koshiji, K.Koshiji, Tokyo University of Science / Japan	WC2-3 Development of High Heat Flux Cooling Jacket for Electronics Devices by using Flow Boiling Y.Shinmoto, Y.Asada, H.Kobayashi, S.Kanazawa, M.Fukagaya, Y.Abe, M.Ouchi, M.Sato, K.Iimura, H.Ohta, Kyushu University / Japan	WD2-3 Determination of Thin-Sisicon Die Strength by Pin-on-Elastic-Foundation Test P.S.Huang, M.Y.Tsai, Chang Gung University / Taiwan R.O.C.
12:40	Lunch Time			

Time	Awarding Ceremony
13:40	Best Paper
	Young Award
	Poster Award

Time	Keynote Speeches	
14:10	1	Opportunities in the Brazilian Microelectronics Market Dr. Claudius Feger, IBM Watson Research Lab / U.S.A.
15:10		
15:20	2	Evolution and Outlook of 3D IC/Si Dr. John Lau, Electronics & Optoelectronics Labs (EOL)Industrial Technology Research Institute / Taiwan
16:20	3	3D Package for Mobile Application Dr. Sayoon Kang, Samsung Electronics / Korea
17:20		

Time	
18:30	Welcome Reception At Restaurant, Nara National Museum
20:30	

Nara National Museum



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